

74HC125

Quad 3-State Noninverting Buffers

High-Performance Silicon-Gate CMOS

The 74HC125 is identical in pinout to the LS125. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC125 noninverting buffer is designed to be used with 3-state memory address drivers, clock drivers, and other bus-oriented systems. The device has four separate output enables that are active-low.

Features

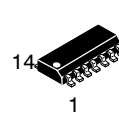
- Output Drive Capability: 15 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the JEDEC Standard No. 7A Requirements
- ESD Performance: HBM > 2000 V; Machine Model > 200 V
- Chip Complexity: 72 FETs or 18 Equivalent Gates
- These are Pb-Free Devices



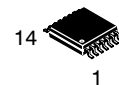
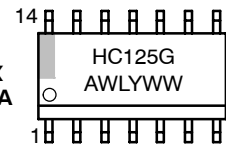
ON Semiconductor®

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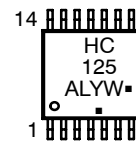
MARKING DIAGRAMS



SOIC-14
D SUFFIX
CASE 751A



TSSOP-14
DT SUFFIX
CASE 948G



A = Assembly Location
L, WL = Wafer Lot
Y = Year
W, WW = Work Week
G or ■ = Pb-Free Package

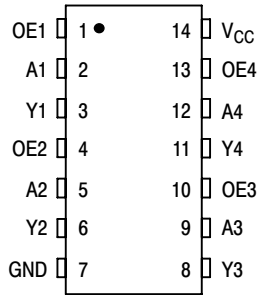
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

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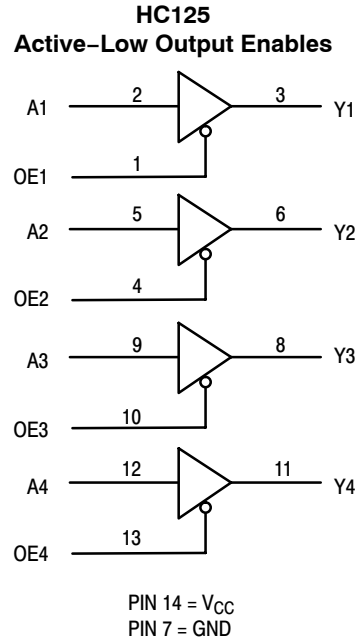
PIN ASSIGNMENT



FUNCTION TABLE

| HC125 | | |
|--------|----|--------|
| Inputs | | Output |
| A | OE | Y |
| H | L | H |
| L | L | L |
| X | H | Z |

LOGIC DIAGRAM



MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|------------------|--|--------------------------------|------|
| V _{CC} | DC Supply Voltage (Referenced to GND) | - 0.5 to + 7.0 | V |
| V _{in} | DC Input Voltage (Referenced to GND) | - 0.5 to V _{CC} + 0.5 | V |
| V _{out} | DC Output Voltage (Referenced to GND) | - 0.5 to V _{CC} + 0.5 | V |
| I _{in} | DC Input Current, per Pin | ±20 | mA |
| I _{out} | DC Output Current, per Pin | ±35 | mA |
| I _{CC} | DC Supply Current, V _{CC} and GND Pins | ±75 | mA |
| P _D | Power Dissipation in Still Air SOIC Package† TSSOP Package† | 500 450 | mW |
| T _{stg} | Storage Temperature | - 65 to + 150 | °C |
| T _L | Lead Temperature, 1 mm from Case for 10 Seconds (SOIC or TSSOP Package) | 260 | °C |

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating — SOIC Package: - 7 mW/°C from 65° to 125°C
TSSOP Package: - 6.1 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

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RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|-------------------|--|-----|----------|------|
| V_{CC} | DC Supply Voltage (Referenced to GND) | 2.0 | 6.0 | V |
| V_{in}, V_{out} | DC Input Voltage, Output Voltage (Referenced to GND) | 0 | V_{CC} | V |
| T_A | Operating Temperature, All Package Types | -55 | +125 | °C |
| t_r, t_f | Input Rise and Fall Time (Figure 1) | | | ns |
| | $V_{CC} = 2.0\text{ V}$ | 0 | 1000 | |
| | $V_{CC} = 4.5\text{ V}$ | 0 | 500 | |
| | $V_{CC} = 6.0\text{ V}$ | 0 | 400 | |

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| Symbol | Parameter | Test Conditions | V_{CC} (V) | Guaranteed Limit | | | Unit |
|----------|--|---|--------------|------------------|--------|---------|------|
| | | | | -55 to 25°C | ≤ 85°C | ≤ 125°C | |
| V_{IH} | Minimum High-Level Input Voltage | $V_{out} = V_{CC} - 0.1\text{ V}$ $ I_{out} \leq 20\ \mu\text{A}$ | 2.0 | 1.5 | 1.5 | 1.5 | V |
| | | | 3.0 | 2.1 | 2.1 | 2.1 | |
| | | | 4.5 | 3.15 | 3.15 | 3.15 | |
| | | | 6.0 | 4.2 | 4.2 | 4.2 | |
| V_{IL} | Maximum Low-Level Input Voltage | $V_{out} = 0.1\text{ V}$ $ I_{out} \leq 20\ \mu\text{A}$ | 2.0 | 0.5 | 0.5 | 0.5 | V |
| | | | 3.0 | 0.9 | 0.9 | 0.9 | |
| | | | 4.5 | 1.35 | 1.35 | 1.35 | |
| | | | 6.0 | 1.8 | 1.8 | 1.8 | |
| V_{OH} | Minimum High-Level Output Voltage | $V_{in} = V_{IH}$ $ I_{out} \leq 20\ \mu\text{A}$ | 2.0 | 1.9 | 1.9 | 1.9 | V |
| | | | 4.5 | 4.4 | 4.4 | 4.4 | |
| | | | 6.0 | 5.9 | 5.9 | 5.9 | |
| | | $V_{in} = V_{IH}$ $ I_{out} \leq 3.6\text{ mA}$ $ I_{out} \leq 6.0\text{ mA}$ $ I_{out} \leq 7.8\text{ mA}$ | 3.0 | 2.48 | 2.34 | 2.2 | |
| | | | 4.5 | 3.98 | 3.84 | 3.7 | |
| | | | 6.0 | 5.48 | 5.34 | 5.2 | |
| V_{OL} | Maximum Low-Level Output Voltage | $V_{in} = V_{IL}$ $ I_{out} \leq 20\ \mu\text{A}$ | 2.0 | 0.1 | 0.1 | 0.1 | V |
| | | | 4.5 | 0.1 | 0.1 | 0.1 | |
| | | | 6.0 | 0.1 | 0.1 | 0.1 | |
| | | $V_{in} = V_{IL}$ $ I_{out} \leq 3.6\text{ mA}$ $ I_{out} \leq 6.0\text{ mA}$ $ I_{out} \leq 7.8\text{ mA}$ | 3.0 | 0.26 | 0.33 | 0.4 | |
| | | | 4.5 | 0.26 | 0.33 | 0.4 | |
| | | | 6.0 | 0.26 | 0.33 | 0.4 | |
| I_{in} | Maximum Input Leakage Current | $V_{in} = V_{CC}$ or GND | 6.0 | ±0.1 | ±1.0 | ±1.0 | μA |
| I_{OZ} | Maximum Three-State Leakage Current | Output in High-Impedance State $V_{in} = V_{IL}$ or V_{IH} $V_{out} = V_{CC}$ or GND | 6.0 | ±0.5 | ±5.0 | ±10 | μA |
| I_{CC} | Maximum Quiescent Supply Current (per Package) | $V_{in} = V_{CC}$ or GND $I_{out} = 0\ \mu\text{A}$ | 6.0 | 4.0 | 40 | 40 | μA |

NOTE: Information on typical parametric values can be found in Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

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AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6.0 ns)

| Symbol | Parameter | V _{CC} (V) | Guaranteed Limit | | | Unit |
|--|---|------------------------|------------------|--------|---------|------|
| | | | - 55 to 25°C | ≤ 85°C | ≤ 125°C | |
| t _{PLH} , t _{PHL} | Maximum Propagation Delay, Input A to Output Y (Figures 1 and 3) | 2.0 | 90 | 115 | 135 | ns |
| | | 3.0 | 36 | 45 | 60 | |
| | | 4.5 | 18 | 23 | 27 | |
| | | 6.0 | 15 | 20 | 23 | |
| t _{PLZ} , t _{PHZ} | Maximum Propagation Delay, Output Enable to Y (Figures 2 and 4) | 2.0 | 120 | 150 | 180 | ns |
| | | 3.0 | 45 | 60 | 80 | |
| | | 4.5 | 24 | 30 | 36 | |
| | | 6.0 | 20 | 26 | 31 | |
| t _{PZL} , t _{PZH} | Maximum Propagation Delay, Output Enable to Y (Figures 2 and 4) | 2.0 | 90 | 115 | 135 | ns |
| | | 3.0 | 36 | 45 | 60 | |
| | | 4.5 | 18 | 23 | 27 | |
| | | 6.0 | 15 | 20 | 23 | |
| t _{TLH} , t _{THL} | Maximum Output Transition Time, Any Output (Figures 1 and 3) | 2.0 | 60 | 75 | 90 | ns |
| | | 3.0 | 22 | 28 | 34 | |
| | | 4.5 | 12 | 15 | 18 | |
| | | 6.0 | 10 | 13 | 15 | |
| C _{in} | Maximum Input Capacitance | - | 10 | 10 | 10 | pF |
| C _{out} | Maximum 3-State Output Capacitance (Output in High-Impedance State) | - | 15 | 15 | 15 | pF |

NOTE: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

| C _{PD} | Power Dissipation Capacitance (Per Buffer)* | Typical @ 25°C, V _{CC} = 5.0 V | | pF |
|-----------------|---|---|--|----|
| | | 30 | | |
| | | | | |

* Used to determine the no-load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}. For load considerations, see Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------|----------------------|-----------------------|
| 74HC125DR2G | SOIC-14 (Pb-Free) | 2500 / Tape & Reel |
| 74HC125DTR2G | TSSOP-14* | 2500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

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SWITCHING WAVEFORMS

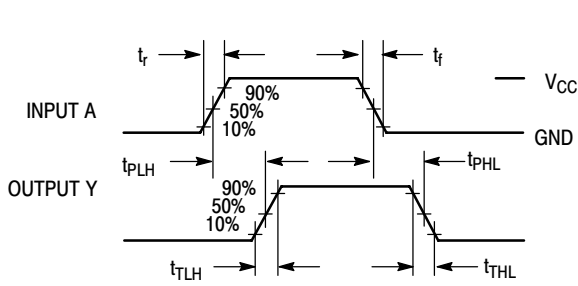


Figure 1.

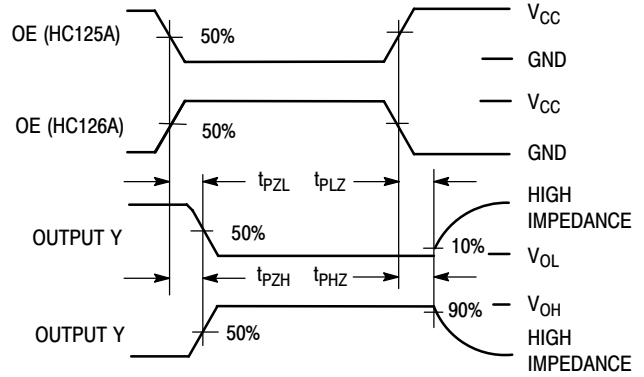
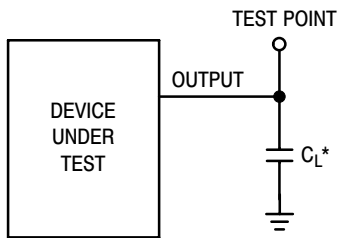
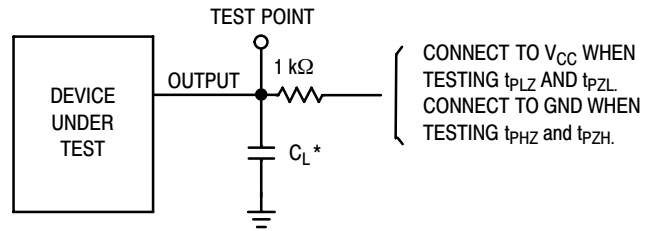


Figure 2.



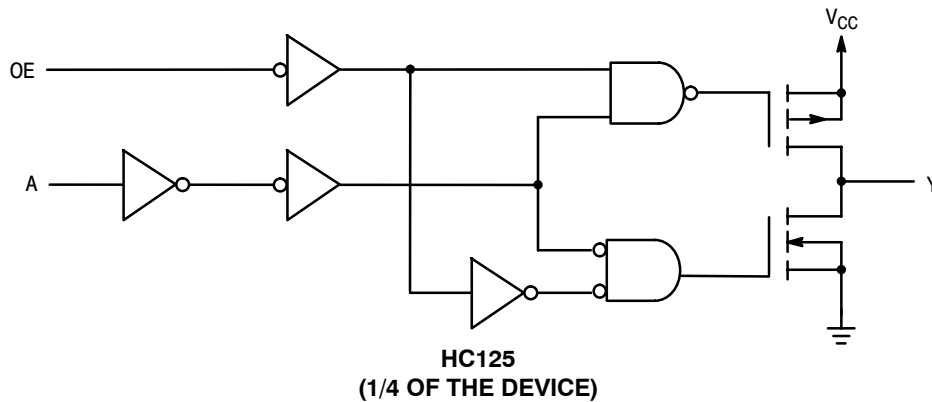
*Includes all probe and jig capacitance

Figure 3. Test Circuit



*Includes all probe and jig capacitance

Figure 4. Test Circuit



HC125
(1/4 OF THE DEVICE)

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PACKAGE DIMENSIONS

SOIC-14
CASE 751A-03
ISSUE H

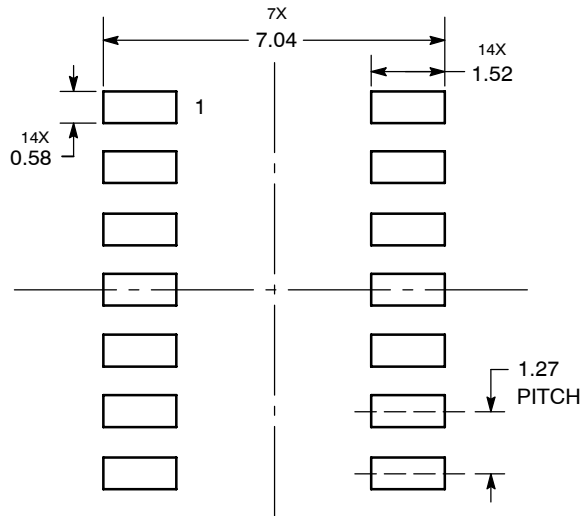


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 8.55 | 8.75 | 0.337 | 0.344 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.054 | 0.068 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.40 | 1.25 | 0.016 | 0.049 |
| G | 1.27 BSC | | 0.050 BSC | |
| J | 0.19 | 0.25 | 0.008 | 0.009 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| M | 0° | 7° | 0° | 7° |
| P | 5.80 | 6.20 | 0.228 | 0.244 |
| R | 0.25 | 0.50 | 0.010 | 0.019 |

SOLDERING FOOTPRINT*



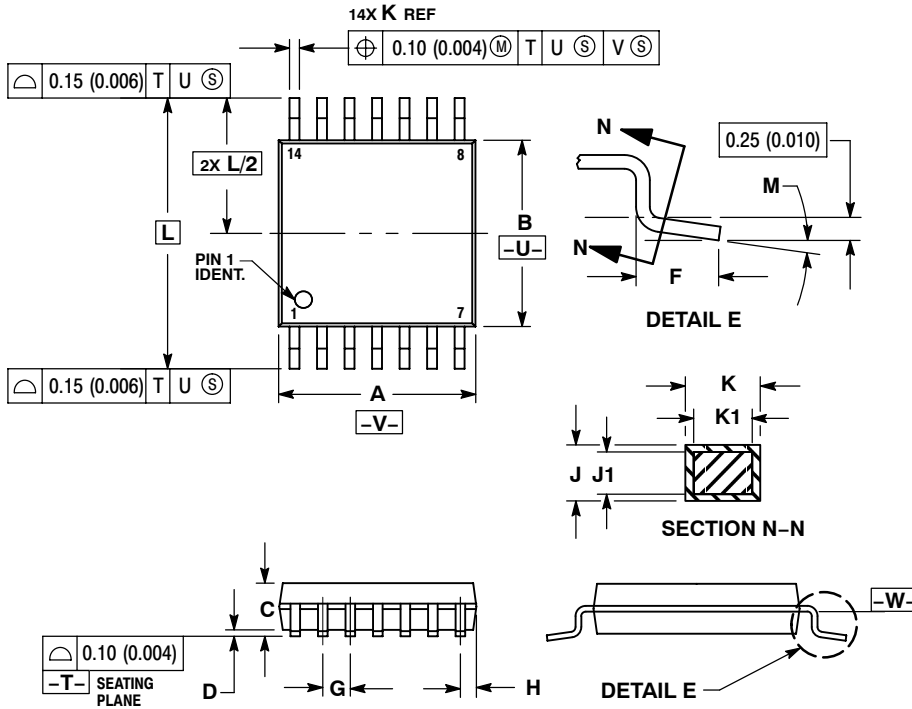
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

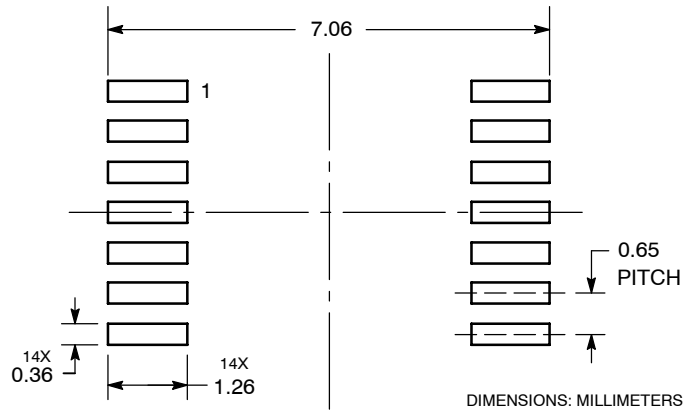
TSSOP-14
CASE 948G-01
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.90 | 5.10 | 0.193 | 0.200 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.20 | --- | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.50 | 0.60 | 0.020 | 0.024 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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